

PMP10222 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C1_Slave1,	8	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1 μF, 16 V, +/- 5%, X7R, 0603	0603
C1_Slave2,						
C1_Slave3, C4,						
C4_Slave1,						
C4_Slave2,						
C4_Slave3						
C2, C2_Slave1,	5	4.7uF	CGA6P3X7R1H475M250AB	TDK	CAP, CERM, 4.7 µF, 50 V, +/- 20%, X7R, AEC-Q200 Grade 1, 1210	1210
C2_Slave2,						
C2_Slave3, C3						
C5, C5_Slave1,	8	2.2uF	GRM31CR61H225KA88L	MuRata	CAP, CERM, 2.2 μF, 50 V, +/- 10%, X5R, 1206	1206
C5_Slave2,						
C5_Slave3, C6,						
C6_Slave1,						
C6_Slave2,						
C6_Slave3						
C7, C7_Slave1,	4	470pF	06031C471JAT2A	AVX	CAP, CERM, 470 pF, 100 V, +/- 5%, X7R, 0603	0603
C7_Slave2,						
C7_Slave3						
C8	1	100uF	EEE-FC1H101P	Panasonic	CAP, AL, 100 μF, 50 V, +/- 20%, 0.3 ohm, SMD	SMT Radial G
C101,	4	1000pF	06031C102JAT2A	AVX	CAP, CERM, 1000 pF, 100 V, +/- 5%, X7R, 0603	0603
C101_Slave1,						
C101_Slave2,						
C101_Slave3						
C102,	4	4.7uF	GRM32ER71H475KA88L	MuRata	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1210	1210
C102_Slave1,						
C102_Slave2,						
C102_Slave3						
D1, D1_Slave1,	4	60V	B260-13-F	Diodes Inc.	Diode, Schottky, 60 V, 2 A, SMB	SMB
D1_Slave2,						
D1_Slave3						
D2, D2_Slave1,	4	3.3V	BZT52C3V3T-7	Diodes Inc.	Diode, Zener, 3.3 V, 300 mW, SOD-523	SOD-523
D2_Slave2,						
D2_Slave3						
DIM, GND, SYNC	3	Double	1573-2	Keystone	Terminal, Turret, TH, Double	Keystone1573-2
J1	1		282834-2	TE Connectivity	Terminal Block, 2x1, 2.54mm, TH	Terminal Block, 2x1, 2.54mm, TH
J2, J3, J4, J5	4		2061-0602_T	WAGO	Terminal Block with Pushbutton, 2-pole, Height 5.6mm, SMD	Terminal Block, 2-
			_			Pole, Body
						11.7x15.2mm
L1	1	2.2uH	744028002	Wurth Elektronik	Inductor, Shielded Drum Core, Ferrite, 2.2 µH, 1 A, 0.125 ohm, SMD	WE-TPC-T
L2, L2_Slave1,	4	47uH	7447714470	Wurth Elektronik	Inductor, Shielded Drum Core, Ferrite, 47 µH, 2.2 A, 0.0825 ohm, SMD	10x5x10mm
L2_Slave2,						
L2_Slave3						

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
L3, L3_Slave1,	8	330 ohm	BLM18SG331TN1D	MuRata	Ferrite Bead, 330 ohm @ 100 MHz, 1.5 A, 0603	0603
L3_Slave2,						
L3_Slave3, L4,						
L4_Slave1,						
L4_Slave2,						
L4_Slave3						
R1, R1_Slave1,	8	232k	CRCW0603232KFKEA	Vishay-Dale	RES, 232 k, 1%, 0.1 W, 0603	0603
R1_Slave2,						
R1_Slave3, R3,						
R3_Slave1,						
R3_Slave2,						
R3_Slave3						
R2, R2_Slave1,	4	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R2_Slave2,						
R2_Slave3						
R4, R4_Slave1,	4	402k	CRCW0603402KFKEA	Vishay-Dale	RES, 402 k, 1%, 0.1 W, 0603	0603
R4_Slave2,						
R4_Slave3						
R6		0.3	CSR2010JTR300	Stackpole Electronics Inc	RES, 0.3, 5%, 1 W, 2010	2010
R6_Slave1,	3	0.33	CSRN2512FKR330	Stackpole Electronics Inc	RES, 0.33, 1%, 2 W, 2512	2512
R6_Slave2,						
R6_Slave3						
R7, R7_Slave1,	4	1.0k	CRCW06031K00JNEA	Vishay-Dale	RES, 1.0 k, 5%, 0.1 W, 0603	0603
R7_Slave2,						
R7_Slave3						
R101,	4	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.1 W, 0603	0603
R101_Slave1,						
R101_Slave2,						
R101_Slave3						
U1, U1_Slave1,	4		TPS92512DGQR	Texas Instruments	TPS92512 2.5A Buck Current Regulator for High-Brightness LEDs with	DGQ0010D
U1_Slave2,					Integrated Analog Current Adjust, DGQ0010D	
U1_Slave3						

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